

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Philip Neaves Attorney Docket No.: 501340.02
Filed : Concurrently Herewith
Title : STRUCTURE AND METHOD FOR FORMING A CAPACITIVELY COUPLED
CHIP-TO-CHIP SIGNALING INTERFACE

INFORMATION DISCLOSURE STATEMENT

Mail Stop Patent Application
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

In accordance with 37 C.F.R. §§ 1.56 and 1.97 through 1.98, applicant wishes to make known to the Patent and Trademark Office the references set forth on the attached form PTO-1449. Copies of the cited foreign patent and non-patent literature references, as required under 37 C.F.R. § 1.98(a)(2), are enclosed. Copies of the cited U.S. patents and U.S. patent application publications will not be submitted herewith in accordance with the waiver by the Office of the requirement under 37 C.F.R. § 1.98(a)(2)(i) for U.S. national patent applications filed after June 30, 2003. Although the aforesaid references are made known to the Patent and Trademark Office in compliance with applicant's duty to disclose all information he is aware of which is believed relevant to the examination of the above-identified application, applicant believes that his invention is patentable.

Applicant also wishes to make known to the Patent and Trademark Office that applications, Serial Nos. 10/666,393, and 10/691,020, describing and claiming subject matter that is similar to the subject matter of this application, were filed on September 17, 2003, and October 21, 2003, respectively. These related applications, as well as any prior art cited therein, may be material to the examination of this application. A copy of these related applications as filed are submitted herewith in accordance with 37 C.F.R. § 1.98(d).

Please acknowledge receipt of this Information Disclosure Statement and kindly make the cited references of record in the above-identified application.

Respectfully submitted,

DORSEY & WHITNEY LLP



Steven H. Arterberry
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SHA:tlm

Enclosures:

Form PTO-1449
Cited References (4)
Copy of Related Application

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FORM PTO-1449 (REV. 7-80)	U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE	ATTY. DOCKET NO. 501340.02	APPLICATION NO. Not Yet Assigned
INFORMATION DISCLOSURE STATEMENT <i>(Use several sheets if necessary)</i>		APPLICANT(S) Philip Neaves	
		FILING DATE Concurrently herewith	GROUP ART UNIT Not Yet Assigned

U.S. PATENT DOCUMENTS

*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	5,673,130	09/30/97	Sundstrom et al.	359	158	
	AB	6,310,494 B1	10/30/01	Ehben et al.	326	82	
	AC	6,425,107 B1	07/23/02	Caldara et al.	714	759	
	AD						
	AE						
	AF						
	AG						
	AH						
	AI						
	AJ						

FOREIGN PATENT DOCUMENTS

		DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
	AK	0366263 A2	05/02/90	EP	H04L	12/56		
	AL	WO 0215185 A1	02/21/02	PCT	G11B	20/14		
	AM							
	AN							
	AO							

OTHER PRIOR ART *(Including Author, Title, Date, Pertinent Pages, Etc.)*

	AP	Scanlan, Christopher M., and Nozad Karim. "System-In-Package Technology, Application and Trends." Amkor Technology, Inc. (No date).
	AQ	Wang, Michael, Katsuharu Suzuki, Wayne Dai, Atsushi Sakai, and Kiwamu Watanabe. "Configurable Area-IO Memory for System-in-a-Package (SiP)." (No date).

EXAMINER /Stephen W. Smoot/	DATE CONSIDERED 02/29/2008
* EXAMINER: Initial if reference considered, whether or not criteria is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant(s).	